



## Material Content Data Sheet



<b>Sales Product Name</b>		BCR 562 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000238834						
<b>Package</b>		PG-SOT23-3-4		<b>Weight*</b>		9.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15	
	noble metal	gold	7440-57-5	0.013	0.14		1439	
	inorganic material	silicon	7440-21-3	0.112	1.23	1.37	12290	13744
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		996	
	inorganic material	silicon	7440-21-3	0.001	0.01		66	
	non noble metal	titanium	7440-32-6	0.003	0.03		332	
	non noble metal	copper	7440-50-8	3.001	33.06	33.20	330570	331964
wire	noble metal	gold	7440-57-5	0.015	0.17	0.17	1683	1683
encapsulation	organic material	carbon black	1333-86-4	0.091	1.00		10008	
	inorganic material	antimonytrioxide	1309-64-4	0.136	1.50		15012	
	plastics	brominated resin	-	0.170	1.88		18765	
	plastics	epoxy resin	-	1.419	15.64		156374	
	inorganic material	silicondioxide	60676-86-0	3.861	42.53	62.55	425337	625496
leadfinish	non noble metal	tin	7440-31-5	0.136	1.50	1.50	15028	15028
plating	noble metal	silver	7440-22-4	0.110	1.21	1.21	12085	12085
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com